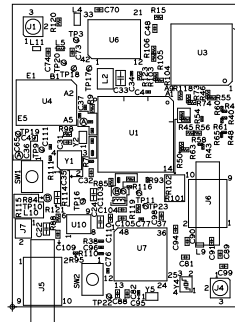
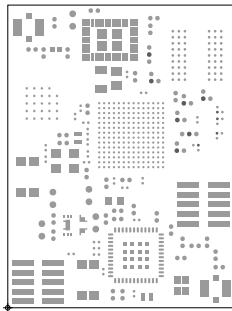


NOTE:

- 1.RECOMMENDED STENCIL THICKNESS - 4MIL
- 2.MARK APPROPRIATE DASH, REV. AND SERIAL NO. CHARACTERS TO BE PERMANENT AND LEGIBLE.
- 3.WORKMANSHIP OF ELECTRONIC ASSEMBLIES SHALL CONFORM TO IPC-A-610, CLASS 2.
- 4.ASSEMBLY IS STATIC SENSITIVE ALL PROCESS/HANDLING OPERATIONS MUST CONFORM TO E.S.D. PRACTICES CONTAINED WITHIN IPC-A-610.





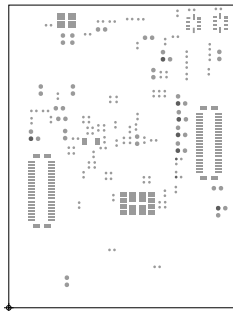
NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: SPT_SOLDER PASTE TOP



NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: SPB_SOLDER PASTE BOTTOM